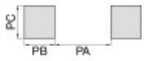
Multilayer Ceramic Chip Capacitors

CGA5L1X8L1E106K160AC New Product

RoHS REACH SVHC-Free Halogen Free Lead Free

TDK item description	CGA5L1X8L1E106KT****
Applications	Automotive Grade
Feature	150°C High Temperature Application AEC-Q200 AEC-Q200
Series	CGA5(3216) [EIA 1206]
Status	Production



Images are for reference only and show exemplary products.

PDF file of this page

Contact

Documents

- Catalog
- Specification
- RoHS Certificate
- SVHC/REACH Certificate Update
- Selection Guide for Automotive MLCC New
- Sample Kits
- Characterization Sheet

Size	
Length(L)	3.20mm +0.30,-0.10mm
Width(W)	1.60mm +0.30,-0.10mm
Thickness(T)	1.60mm +0.30,-0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	1.00mm Min.
Recommended Land Pattern (PA)	2.10mm to 2.50mm(Flow Soldering) 2.00mm to 2.40mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.10mm to 1.30mm(Flow Soldering) 1.00mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PC)	1.00mm to 1.30mm(Flow Soldering) 1.10mm to 1.60mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	10µF ±10%
Rated Voltage	25VDC
Temperature Characteristic	X8L(+15,-40%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	50MΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

Impedance	ESR

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CGA5L1X8L1E106K160AC

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Capacitance

CGA5L1X8L1E106K160AC

Change settings

DC Bias Characteristic

CGA5L1X8L1E106K160AC

Change settings

Temperature Characteristic

CGA5L1X8L1E106K160AC(No Bias) CGA5L1X8L1E106K160AC(DC Bias = 12.5)

Change settings

Ripple Temperature Rising

CGA5L1X8L1E106K160AC(100 kHz) CGA5L1X8L1E106K160AC(500 kHz) CGA5L1X8L1E106K160AC(1 MHz)

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